

Data Sheet January 2002

## 8A, 400V - 600V Hyperfast Dual Diodes

The RHRP840CC and RHRP860CC are hyperfast dual diodes with soft recovery characteristics ( $t_{rr} < 30 \text{ns}$ ). They have half the recovery time of ultrafast diodes and are of silicon nitride passivated ion-implanted epitaxial planar construction.

These devices are intended for use as freewheeling/ clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

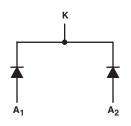
Formerly development type TA49059.

# **Ordering Information**

PART NUMBER	PACKAGE	BRAND
RHRP840CC	TO-220AB	RHRP840C
RHRP860CC	TO-220AB	RHRP860C

NOTE: When ordering, use the entire part number.

## Symbol



### **Features**

•	Hyperfast with Soft Recovery <30ns
•	Operating Temperature
•	Reverse Voltage Up To
	A

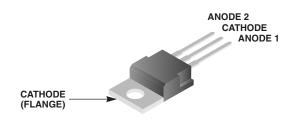
- Avalanche Energy Rated
- Planar Construction

## **Applications**

- · Switching Power Supplies
- · Power Switching Circuits
- · General Purpose

## **Packaging**

**JEDEC TO-220AB** 



Absolute Maximum Ratings (Per Leg) $T_C = 25^{\circ}C$ , Unless Otherwise Specified			
	RHRP840CC	RHRP860CC	UNITS
Peak Repetitive Reverse Voltage	400	600	V
Working Peak Reverse Voltage	400	600	V
DC Blocking Voltage V <sub>R</sub>	400	600	V
Average Rectified Forward Current $I_{F(AV)}$ ( $T_C = 150^{\circ}C$ )	8	8	Α
Repetitive Peak Surge Current	16	16	Α
Nonrepetitive Peak Surge Current	100	100	Α
Maximum Power Dissipation	75	75	W
Avalanche Energy (See Figures 10 and 11)	20	20	mJ
Operating and Storage Temperature	-65 to 175	-65 to 175	°C

## RHRP840CC, RHRP860CC

**Electrical Specifications** (Per Leg)  $T_C = 25^{\circ}C$ , Unless Otherwise Specified

			RHRP840CC		RHRP860CC			
SYMBOL	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 8A	-	-	2.1	-	-	2.1	V
	I <sub>F</sub> = 8A, T <sub>C</sub> = 150°C	-	-	1.7	-	-	1.7	V
I <sub>R</sub>	V <sub>R</sub> = 400V	-	-	100	-	-	-	μА
	V <sub>R</sub> = 600V	-	-	-	-	-	100	μА
	V <sub>R</sub> = 400V, T <sub>C</sub> = 150°C	-	-	500	-	-	-	μА
	V <sub>R</sub> = 600V, T <sub>C</sub> = 150°C	-	-	-	-	-	500	μА
t <sub>rr</sub>	I <sub>F</sub> = 1A, dI <sub>F</sub> /dt = 200A/μs	-	-	30	-	-	30	ns
	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	-	35	-	-	35	ns
ta	$I_F = 8A$ , $dI_F/dt = 200A/\mu s$	-	18	-	-	18	-	ns
t <sub>b</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	10	-	-	10	-	ns
Q <sub>RR</sub>	$I_F = 8A$ , $dI_F/dt = 200A/\mu s$	-	56	-	-	56	-	nC
CJ	V <sub>R</sub> = 10V, I <sub>F</sub> = 0A	-	25	-	-	25	-	pF
$R_{ heta JC}$		-	-	2	-	-	2	°C/W

### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

I<sub>R</sub> = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a + t_b$ .

 $t_a$  = Time to reach peak reverse current (See Figure 9).

 $t_{b}$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

Q<sub>RR</sub> = Reverse recovery charge.

 $C_J$  = Junction Capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

# **Typical Performance Curves**

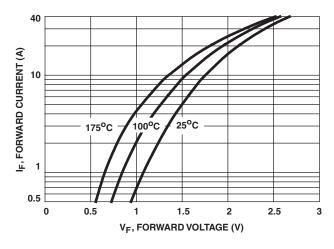


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

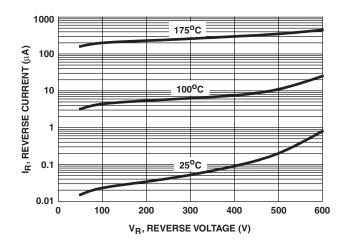


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

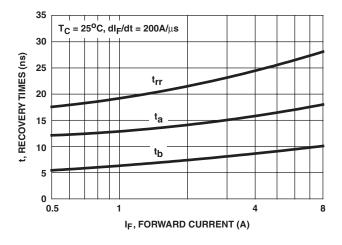


FIGURE 3. t<sub>rr</sub>, t<sub>a</sub> AND t<sub>b</sub> CURVES vs FORWARD CURRENT

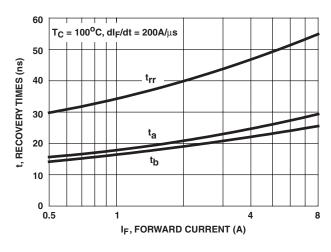


FIGURE 4.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

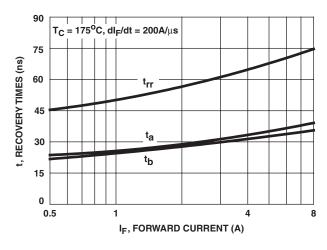


FIGURE 5.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

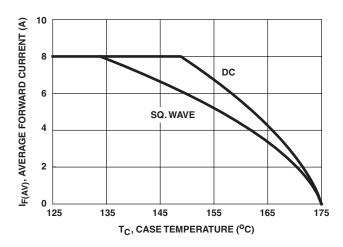


FIGURE 6. CURRENT DERATING CURVE

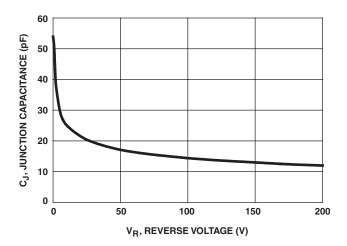


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

## Test Circuits and Waveforms

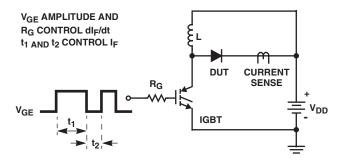


FIGURE 8.  $t_{rr}$  TEST CIRCUIT

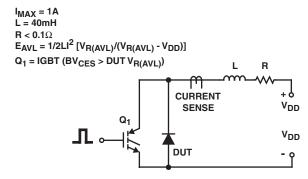


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

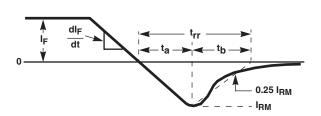


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

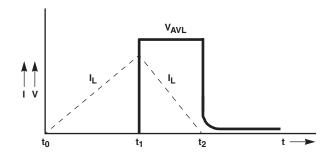


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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